

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6092867

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the CONVEYING PARTY DATA IN EPAS COVER SHEET: INVENTOR 3 NAME SHOULD BE HAO XU. previously recorded on Reel 052143 Frame 0416. Assignor(s) hereby confirms the INVENTOR 3 NAME IS HAO XU..
CONVEYING PARTY DATA	
Name	Execution Date
CHONG LI	12/15/2017
JUNYI LI	12/15/2017
HAO XU	01/10/2018
JING JIANG	01/10/2018
RECEIVING PARTY DATA	
Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16821913
CORRESPONDENCE DATA	
Fax Number:	(202)857-6395
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	213-629-7400
Email:	rachele.wittwer@arentfox.com, patentdocket@arentfox.com
Correspondent Name:	ARENT FOX, LLP AND QUALCOMM, INCORPORATED
Address Line 1:	1717 K STREET, NW
Address Line 4:	WASHINGTON, D.C. 20006-5344
ATTORNEY DOCKET NUMBER:	030284.18201/171061C1
NAME OF SUBMITTER:	RACHELE WITTTWER
SIGNATURE:	/Rachele Witttwer/
DATE SIGNED:	05/05/2020
Total Attachments: 10	

source=171061C1 Corrective Assignment#page1.tif
source=171061C1 Corrective Assignment#page2.tif
source=171061C1 Corrective Assignment#page3.tif
source=171061C1 Corrective Assignment#page4.tif
source=171061C1 Corrective Assignment#page5.tif
source=171061C1 Corrective Assignment#page6.tif
source=171061C1 Corrective Assignment#page7.tif
source=171061C1 Corrective Assignment#page8.tif
source=171061C1 Corrective Assignment#page9.tif
source=171061C1 Corrective Assignment#page10.tif

**United States Patent and Trademark Office**

Home | Site Index | Search | Guides | Contacts | eBusiness | eBiz alerts | News | Help

*Electronic Patent Assignment System***Confirmation Receipt**

Your assignment has been received by the USPTO.
The coversheet of the assignment is displayed below:

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHONG LI</td> <td>12/15/2017</td> </tr> <tr> <td>JUNYI LI</td> <td>12/15/2017</td> </tr> <tr> <td>HAO XU XU</td> <td>01/10/2018</td> </tr> <tr> <td>JING JIANG</td> <td>01/10/2018</td> </tr> </tbody> </table>		Name	Execution Date	CHONG LI	12/15/2017	JUNYI LI	12/15/2017	HAO XU XU	01/10/2018	JING JIANG	01/10/2018
Name	Execution Date										
CHONG LI	12/15/2017										
JUNYI LI	12/15/2017										
HAO XU XU	01/10/2018										
JING JIANG	01/10/2018										
RECEIVING PARTY DATA											
Name:	QUALCOMM INCORPORATED										
Street Address:	5775 MOREHOUSE DRIVE										
City:	SAN DIEGO										
State/Country:	CALIFORNIA										
Postal Code:	92121-1714										
PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>16821913</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	16821913						
Property Type	Number										
Application Number:	16821913										
CORRESPONDENCE DATA											

PATENT**REEL: 052580 FRAME: 0447**

Fax Number: (202)857-6395
Phone: 213-629-7400
Email: patentdocket@arentfox.com, rachele.wittwer@arentfox.com
Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.
Correspondent Name: ARENT FOX, LLP AND QUALCOMM, INCORPORATED
Address Line 1: 1717 K STREET, NW
Address Line 4: WASHINGTON, D.C. 20006-5344

ATTORNEY DOCKET NUMBER:

030284.18201/171061C1

NAME OF SUBMITTER:

RACHELE WITTWER

Signature:

/Rachele Wittwer/

Date:

03/17/2020

Total Attachments: 6

source=171061C1 Signed Assignment from Prior Application#page1.tif
 source=171061C1 Signed Assignment from Prior Application#page2.tif
 source=171061C1 Signed Assignment from Prior Application#page3.tif
 source=171061C1 Signed Assignment from Prior Application#page4.tif
 source=171061C1 Signed Assignment from Prior Application#page5.tif
 source=171061C1 Signed Assignment from Prior Application#page6.tif

RECEIPT INFORMATION

EPAS ID: PAT6018919
Receipt Date: 03/17/2020

[Return to home page](#)

| [HOME](#) | [INDEX](#) | [SEARCH](#) | [eBUSINESS](#) | [CONTACT US](#) | [PRIVACY STATEMENT](#)

ASSIGNMENT

WHEREAS, WE,

1. **Chong LI**, a citizen of the **People's Republic of China**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**, and a resident of **Weehawken, New Jersey**,
2. **Junyi LI**, a citizen of the **United States of America**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**, and a resident of **Chester, New Jersey**,
3. **Hao XU**, a citizen of the **United States of America**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**, and a resident of **Beijing, China**,
4. **Jing JIANG**, a citizen of the **People's Republic of China**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**, and a resident of **San Diego, California**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **SUBSLLOT BUNDLING AND ACKNOWLEDGEMENT** (collectively the "**INVENTIONS**") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**, desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No(s). **15/789,489** filed **October 20, 2017**, Qualcomm Reference No. **171061**, and all provisional applications relating thereto, together with U.S. Provisional Application No(s). **62/435,518**, filed **December 16, 2016**, Qualcomm Reference No. **171061P1**, (and do hereby authorize **ASSIGNEE** and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

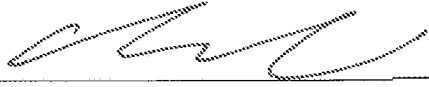
AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

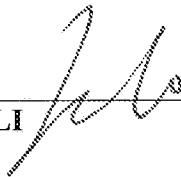
AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Bridgewater, NJ, on 12-15-17
LOCATION DATE


Chong LI

Done at Bridgewater, NJ, on 12-15-17
LOCATION DATE


Junyi LI

Done at _____, on _____
LOCATION DATE

Hao XU

Done at _____, on _____
LOCATION DATE

Jing JIANG

ASSIGNMENT

WHEREAS, WE,

1. **Chong LI**, a citizen of the **People's Republic of China**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**, and a resident of **Weehawken, New Jersey**,
2. **Junyi LI**, a citizen of the **United States of America**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**, and a resident of **Chester, New Jersey**,
3. **Hao XU**, a citizen of the **United States of America**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**, and a resident of **Beijing, China**,
4. **Jing JIANG**, a citizen of the **People's Republic of China**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121-1714**, and a resident of **San Diego, California**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **SUBSLLOT BUNDLING AND ACKNOWLEDGEMENT** (collectively the “**INVENTIONS**”) for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter “**ASSIGNEE**”), a Delaware corporation, having a place of business at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**, desires to acquire or otherwise obtain the entire right, title, and interest in and to said **INVENTIONS**, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto **ASSIGNEE**, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said **INVENTIONS**, including all patent applications therefor that may have been filed or may be filed hereafter for said **INVENTIONS** in the United States, including but not limited to U.S. Application No(s). **15/789,489** filed **October 20, 2017**, Qualcomm Reference No. **171061**, and all provisional applications relating thereto, together with U.S. Provisional Application No(s). **62/435,518**, filed **December 16, 2016**, Qualcomm Reference No. **171061P1**, (and do hereby authorize **ASSIGNEE** and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

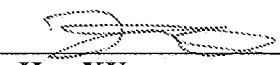
AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

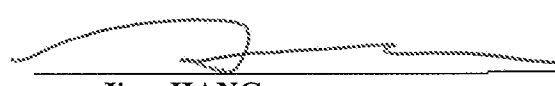
AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Chong LI

Done at _____, on _____
LOCATION DATE Junyi LI

Done at San Diego, on 1/10/2018
LOCATION DATE 
Hao XU

Done at San Diego, on 1/10/2018
LOCATION DATE 
Jing JIANG